

Statement under Article 19(1)

Claim 1 is amended to clearly recite "the electric wiring electrically connects the optical device and the input/output IC so as to transfer an electric signal between them, and the electric wiring positioned on a surface opposite to a surface where the optical device is mounted is provided as a ground electrode and serves as an electromagnetic shield for the optical device and the input/output IC".

A cited reference (Japanese Patent Application Laid-open No. 2-196476) discloses a feature that an LED chip is flip-chip mounted on the substrate, and another cited reference (Japanese Utility Model Application Laid-open No. 63-170141) discloses a feature of letting lights from the LED emitting part pass through the transparent substrate.

The present invention has such a feature that "the electric wiring positioned on a surface opposite to a surface where the optical device is mounted is provided as a ground electrode and serves as an electromagnetic shield for the optical device and the input/output IC", whereby it can also be used as an electromagnetic shield. Therefore, the present invention achieved an effect of realizing electromagnetic shield at low cost.